

Electronic Patent Application Fee Transmittal

Application Number:	10581395			
Filing Date:	14-Aug-2008			
Title of Invention:	Chip Scale Package and Method of Assembling the Same			
First Named Inventor/Applicant Name:	Hien Boon Tan			
Filer:	Carl Joseph Pellegrini/ruth swanson			
Attorney Docket Number:	Q78657			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Request for continued examination	1801	1	810	810
Total in USD (\$)				810